

### Technical Data Sheet 0603 Package Infrared Chip LED SIR19-315/TR8

#### Features

- Small double-end package
- Peak wavelength  $\lambda_p=870\text{nm}$
- Package in 8mm tape on 7" diameter reel
- Compatible with infrared and vapor phase reflow solder process.
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

#### Description

SIR19-315/TR8 is an infrared emitting diode in miniature SMD package which is molded in a water clear epoxy. The device is spectrally matched with silicon photodiode and phototransistor.

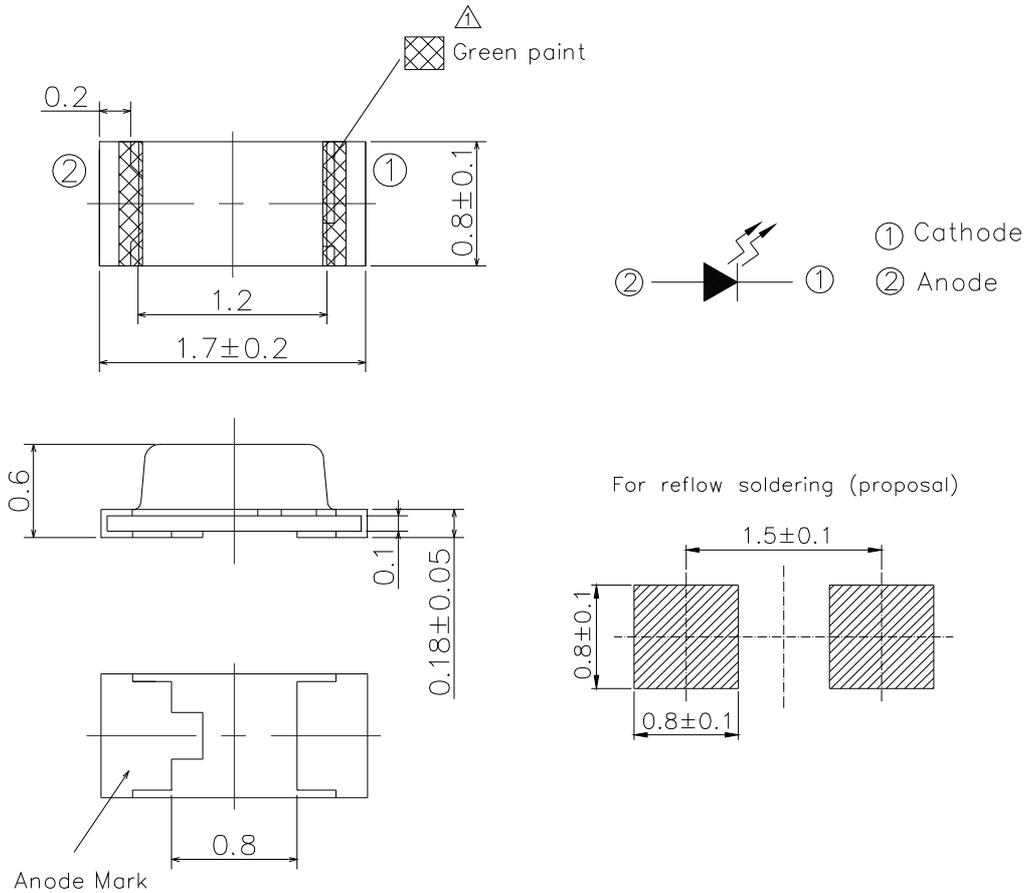
#### Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Scanner
- Infrared applied system

#### Device Selection Guide

| Device No.    | Chip Material | Lens Color  |
|---------------|---------------|-------------|
| SIR19-315/TR8 | AlGaAs        | Water clear |

**Package Dimensions**



- Notes:** 1.All dimensions are in millimeters  
2.Tolerances unless dimensions  $\pm 0.1$ mm

**Absolute Maximum Ratings (Ta=25°C)**

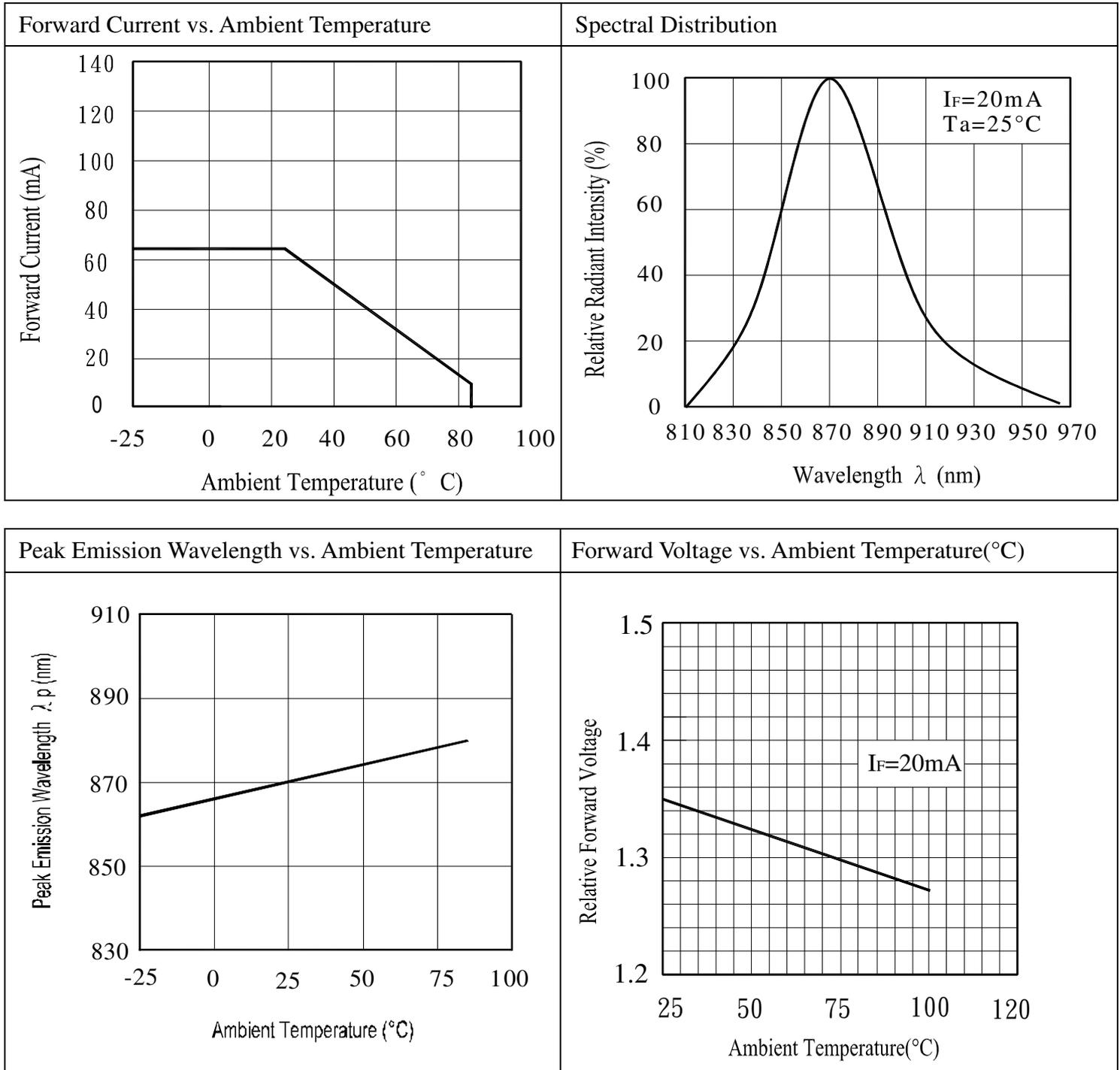
| Parameter   | Symbol    | Rating     | Unit |
|---|-----------|------------|------|
| Continuous Forward Current                                  | $I_F$     | 65         | mA   |
| Reverse Voltage   | $V_R$     | 5          | V    |
| Operating Temperature                                       | $T_{opr}$ | -25 ~ +85  | °C   |
| Storage Temperature   | $T_{stg}$ | -40 ~ +100 | °C   |
| Soldering Temperature *1                                    | $T_{sol}$ | 260        | °C   |
| Power Dissipation at(or below)<br>25°C Free Air Temperature | $P_c$     | 110        | mW   |

**Notes: \*1:Soldering time  $\leq 5$  seconds.**

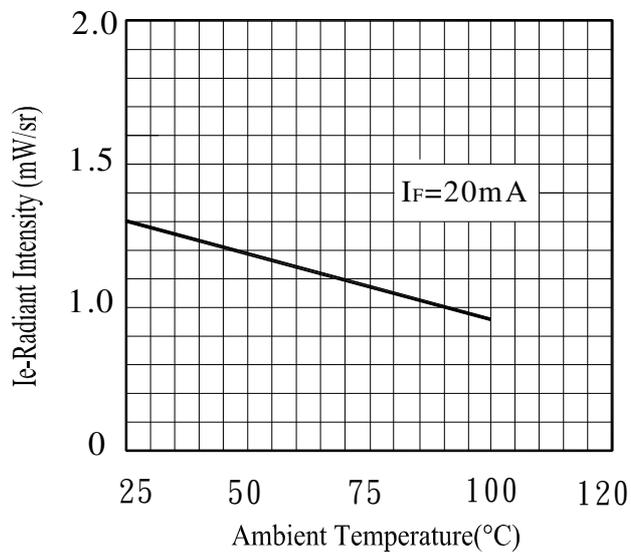
**Electro-Optical Characteristics (Ta=25°C unless specified otherwise)**

| Parameter          | Symbol           | Min. | Typ.* | Max. | Unit    | Condition  |
|--------------------|------------------|------|-------|------|---------|------------|
| Radiant Intensity  | $I_E$            | 1.0  | 1.3   | --   | mW/sr   | $I_F=20mA$ |
| Peak Wavelength    | $\lambda_p$      | 860  | 870   | 900  | nm      | $I_F=20mA$ |
| Spectral Bandwidth | $\Delta \lambda$ | --   | 45    | --   | nm      | $I_F=20mA$ |
| Forward Voltage    | $V_F$            | 1.20 | 1.35  | 1.70 | V       | $I_F=20mA$ |
| Reverse Current    | $I_R$            | --   | --    | 10   | $\mu A$ | $V_R=5V$   |
| View Angle         | $2\theta_{1/2}$  | --   | 140   | --   | Deg.    | $I_F=20mA$ |

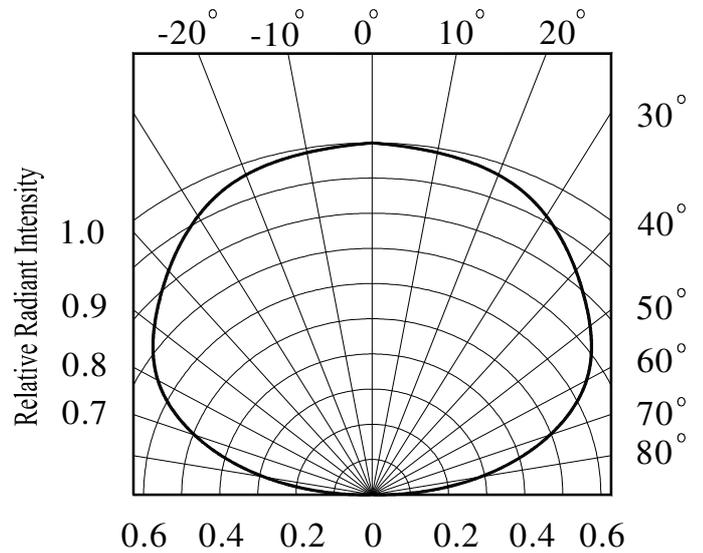
Typical Electrical/Optical/Characteristics Curves



Relative Intensity vs. Ambient Temperature(°C)



Relative Radiant Intensity vs. Angular Displacement



## Precautions For Use

### 1. Over-current-proof

Customer must apply resistors for protection , otherwise slight voltage shift will cause big current change ( Burn out will happen ).

### 2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.

2.3 The LEDs should be used within a year.

2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.

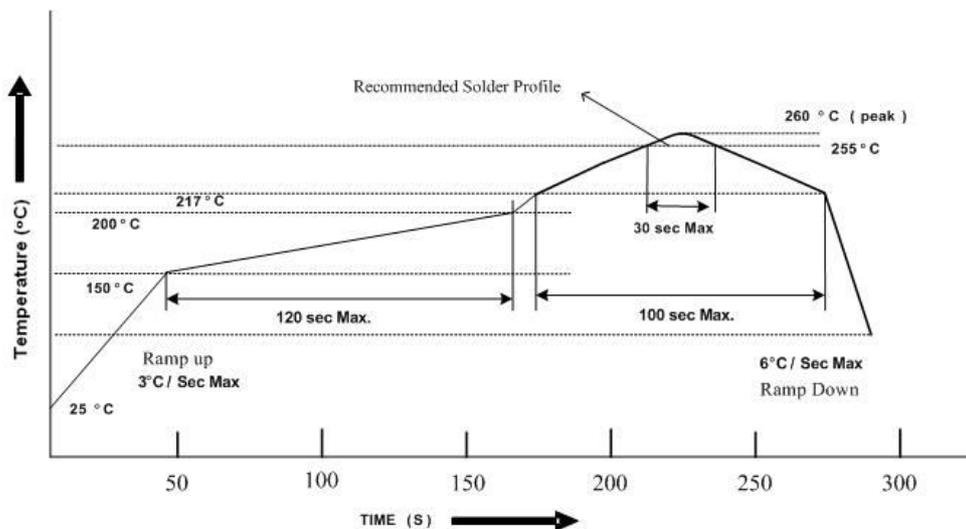
2.5 The LEDs should be used within 168 hours (7 days) after opening the package

2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for Min. 24 hours.

### 3. Soldering Condition

#### 3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

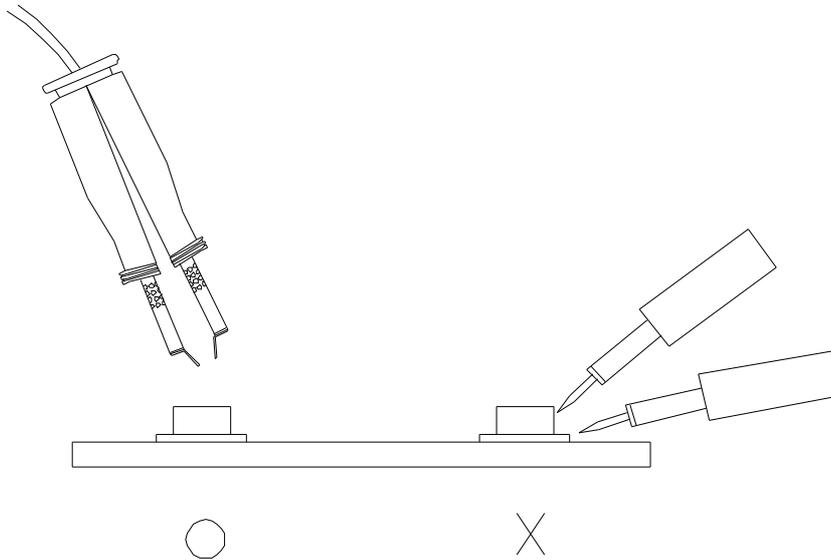
3.4 After soldering, do not warp the circuit board.

#### 4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

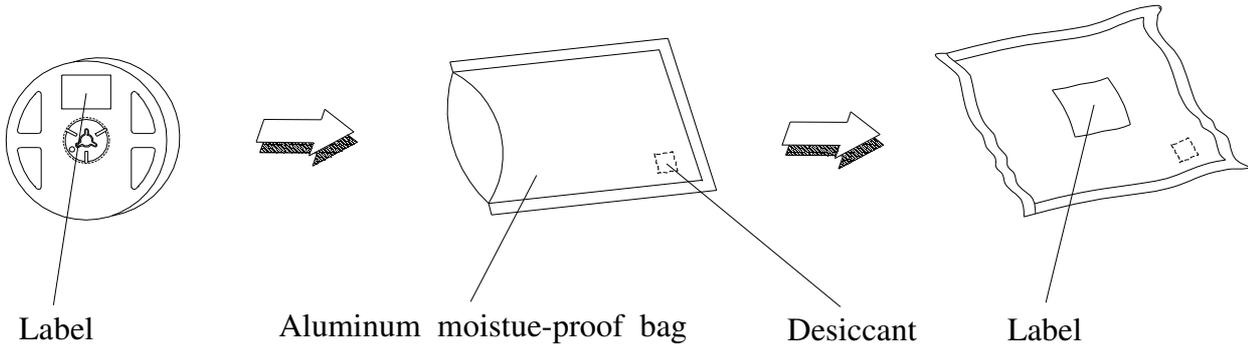
#### 5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

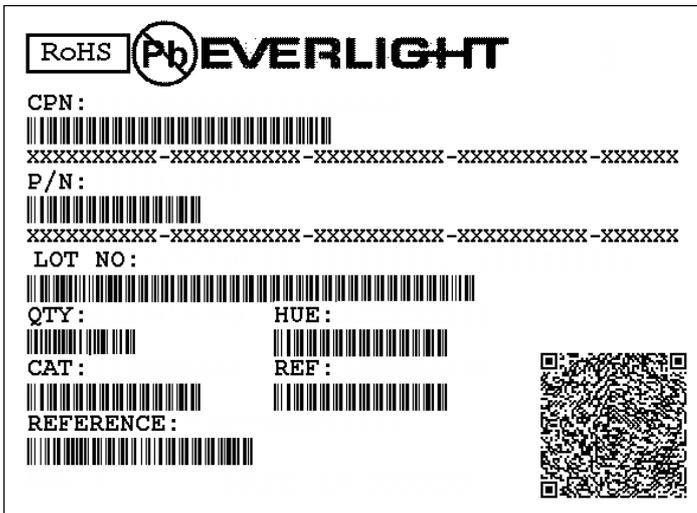




**Packing Procedure**



**Label Form Specification**



CPN: Customer's Production Number

P/N : Production Number

QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

**DISCLAIMER**

1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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